# **Special Issue**

# Machine Vision and 3D Sensing in Smart Agriculture

## Message from the Guest Editors

In recent decades, machine vision and 3D sensing technologies have enabled precision agriculture practices. This Special Issue focuses on agricultural problems, machine vision, and 3D sensing techniques applied to smart or precision agriculture for plant phenotyping, crop monitoring, stress detection, yield prediction, fruit or vegetable quality detection, etc. Traditional and advanced sensing technologies, including visible imaging, near-infrared image, multispectral imaging, hyperspectral imaging, remote sensing, structured light, laser radar, and binocular vision, are increasingly used for various agricultural applications. The Special Issue highlights these technologies for increasing agricultural productivity, reducing resource wastage, and mitigating environmental impacts. Overall, the Special Issue provides valuable insights into the current status and future directions of machine vision and 3D sensing in smart agriculture.

### **Guest Editors**

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Dr. Yuwei Wang

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## Deadline for manuscript submissions

closed (15 January 2024)



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#### Editor-in-Chief

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